

P54/74PCT827A/B P54/74PCT828A/B BUFFERS

PRELIMINARY

T-52-07

★ FEATURES

- Equivalent to Am29827-28 Bipolar Buffers
- Full CMOS Implementation
- Low Power Operation
- High Speed Buffers
- Fully TTL Compatible Input and Output Levels
- $I_{OL} = 48\text{mA}$ (Commercial) and 32mA (Military)
- Clamp Diodes on all Inputs for Ringing Suppression
- Produced with PACE Technology™
- Compact Pinout
 - 24-Pin 300 mil DIP, SOIC
 - 28-Pad 450 mil sq. LCC

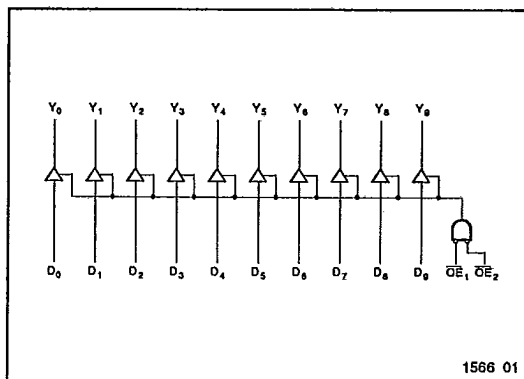
★ DESCRIPTION

The P54/74PCT827A/B and P54/74PCT828A/B 10-bit bus drivers provide high-performance bus interface buffering for wide data/address paths or buses carrying parity. The 10-bit buffers have NOR-ed output enables for maximum control flexibility. All buffer data inputs have 200mV minimum input hysteresis to provide improved noise rejection. The P54/74PCT827A/B and P54/74PCT828A/B family of devices are designed for high-capacitance load drive capability, while providing low-capacitance bus loading at both inputs and outputs. All inputs have clamp diodes and all outputs are designed for low-capacitance bus loading in the high impedance state.

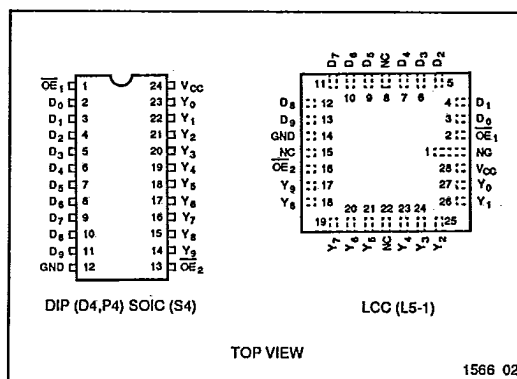
The P54/74PCT827A/B and P54/74PCT828A/B is manufactured using PACE Technology™ which is Performance Advanced CMOS Engineered™ to use 0.8 micron effective channel lengths giving 500 picoseconds loaded* internal gate delays. PACE Technology includes two-level metal and epitaxial substrates. In addition to very high performance and very high density, the technology features latch-up protection, single event upset protection, and is supported by a Class 1 environment volume production facility.

*For a fan-in/fan-out of 4, at 85°C junction temperature and 5.0V supply. For a fan-in/fan-out of 1, the internal gate delay is 200 picoseconds at room temperature and 5.0V

★ LOGIC BLOCK DIAGRAM



PIN CONFIGURATIONS





ABSOLUTE MAXIMUM RATINGS^(1,2)

Symbol	Parameter	Value	Unit
T _{STG}	Storage Temperature	-65 to +150	°C
T _A	Ambient Temperature Under Bias	-55 to +125	°C
V _{CC}	V _{CC} Potential to Ground	-0.5 to +7.0	V
I _{IN}	Input Current	-30 to +5.0	mA

Notes: 1566 Tbl 01
1. Operation beyond the limits set forth in the above table may impair the useful life of the device. Unless otherwise noted, these limits are over the operating free-air temperature range.

RECOMMENDED OPERATING CONDITIONS

Free Air Ambient Temperature	Min	Max
Military	-55°C	+125°C
Commercial	0°C	+70°C

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Symbol	Parameter	Value	Unit
I _{OUTPUT}	Current Applied to Output	100	mA
V _{IN}	Input Voltage	-0.5 to V _{CC} + 0.5	V
V _{OUT}	Voltage Applied to Output	-0.5 to V _{CC} + 0.5	V

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2. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.

Supply Voltage (V _{CC})	Min	Max
Military	+4.5V	+5.5V
Commercial	+4.75V	+5.25V

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DC ELECTRICAL CHARACTERISTICS (Over recommended operating conditions)

Symbol	Parameter	Min	Typ ¹	Max	Units	V _{CC}	Conditions
V _{IH}	Input HIGH Voltage	2.0		V _{CC} + 0.5	V		
V _{IL}	Input LOW Voltage	-0.5		0.8	V		
V _H	Hysteresis		.35		V		All inputs
V _{CD}	Input Clamp Diode Voltage			-1.2	V	MIN	I _{IN} = -18mA
V _{OH}	Output HIGH Voltage	V _{CC} = 3V, V _{IN} = 0.2V, or V _{CC} - 0.2V		V _{CC} - 0.2	V		I _{OH} = -32μA
		Military/Commercial (CMOS)		V _{CC} - 0.2	V	MIN	I _{OH} = -300μA
		Military (TTL)		2.4	V	MIN	I _{OH} = -15mA
		Commercial (TTL)		2.7	V	MIN	I _{OH} = -24mA
V _{OL}	Output LOW Voltage	V _{CC} = 3V, V _{IN} = 0.2V, or V _{CC} - 0.2V		0.2	V		I _{OL} = 300μA
		Military/Commercial (CMOS)		0.2	V	MIN	I _{OL} = 300μA
		Military (TTL)		0.5	V	MIN	I _{OL} = 32mA
		Commercial (TTL)		0.5	V	MIN	I _{OL} = 48mA
I _{IH}	Input HIGH Current			5	μA	MAX	V _{IN} = V _{CC}
I _{IL}	Input LOW Current			-5	μA	MAX	V _{IN} = GND
I _{IH}	Input HIGH Current ³			5	μA	MAX	V _{IN} = 2.7V
I _{IL}	Input LOW Current ³			-5	μA	MAX	V _{IN} = 0.5V
I _{OZH}	Off State I _{OUT} HIGH-Level Voltage Applied			10	μA	MAX	V _{OUT} = V _{CC}
I _{OZL}	Off State I _{OUT} LOW-Level Voltage Applied			-10	μA	MAX	V _{OUT} = GND
I _{OZH}	Off State I _{OUT} HIGH-Level Voltage Applied ³			10	μA	MAX	V _{OUT} = 2.7V
I _{OZL}	Off State I _{OUT} LOW-Level Voltage Applied ³			-10	μA	MAX	V _{OUT} = 0.5V
I _{OS}	Output Short Circuit Current ²	-60			mA	MAX	V _{OUT} = 0.0V
C _{IN}	Input Capacitance ³		5	10	pF	MAX	All inputs
C _{OUT}	Output Capacitance ³		9	12	pF	MAX	All outputs

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Notes:
1. Typical limits are at V_{CC} = 5.0V, T_A = +25°C ambient.
2. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect

operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

3. This parameter is guaranteed but not tested.

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DC CHARACTERISTICS (Over recommended operating conditions unless otherwise specified.)

Symbol	Parameter	Typ ¹	Max	Units	Conditions
I_{CCQC}	Quiescent Power Supply Current (CMOS Inputs) Com'l Mil	.003 .003	0.3 0.5	mA mA	$V_{CC} = \text{MAX}$, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$, $f = 0$, Outputs Open
I_{CCQT}	Quiescent Power Supply Current (TTL inputs)		2.0	mA	$V_{CC} = \text{MAX}$, $V_{IN} = 3.4V^2$, $f = 0$, Outputs Open
I_{CCD}	Dynamic Power Supply Current ³		0.25	mA/ mHz	$V_{CC} = \text{MAX}$, One Input Toggling, 50% Duty Cycle, $\overline{OE} = \text{GND}$, $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$, Outputs Open, $T/R = V_{CC}$ or GND
I_{CC}	Total Power Supply Current ⁵		4.0	mA	$V_{CC} = \text{MAX}$, 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 10\text{MHz}$, $\overline{OE} = \text{GND}$ and $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
			5.0	mA	$V_{CC} = \text{MAX}$, 50% Duty Cycle, Outputs Open, One Bit Toggling at $f_1 = 10\text{MHz}$, $\overline{OE} = \text{GND}$ and $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$
			6.5 ⁴	mA	$V_{CC} = \text{MAX}$, 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 2.5\text{MHz}$, $\overline{OE} = \text{GND}$ and $V_{IN} \leq 0.2V$ or $V_{IN} \geq V_{CC} - 0.2V$
			14.5 ⁴	mA	$V_{CC} = \text{MAX}$, 50% Duty Cycle, Outputs Open, Eight Bits Toggling at $f_1 = 2.5\text{MHz}$, $\overline{OE} = \text{GND}$ and $V_{IN} = 3.4V$ or $V_{IN} = \text{GND}$

Notes:

- Typical values are at $V_{CC} = 5.0V$, $+25^\circ\text{C}$ ambient and maximum loading.
- Per TTL driven input ($V_{IN} = 3.4V$); all other inputs at V_{CC} or GND.
- This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
- Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.
- $I_{CC} = I_{CCQC} + I_{CCQT} + I_{CCD}$
 $I_{CC} = I_{CCQC} + I_{CCQT} D_H N_T + I_{CCD} (f_1/2 + f_1 N_1)$
 I_{CCQC} = Quiescent Current with CMOS input levels

I_{CCQT} = Power Supply Current for a TTL High Input ($V_{IN} = 3.4V$)

D_H = Duty Cycle for TTL Inputs High

N_T = Number of TTL Inputs at D_H

I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

f_1 = Clock Frequency for Register Devices (Zero for Non-Register Devices)

f_1 = Input Frequency

N_1 = Number of Inputs at f_1

All currents are in milliamperes and all frequencies are in megahertz.

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FUNCTION TABLES**P54/74PCT827A/B (Non-Inverting)**

Inputs			Outputs	Function
$\overline{OE}_1$	$\overline{OE}_2$	D_1	Y_1	
L	L	L	L	Transparent
L	L	H	H	
H	X	X	Z	Three-State
X	H	X	Z	

Note:

H = High, L = Low, X = Don't Care, Z = High Impedance

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P54/74PCT828A/B (Inverting)

Inputs			Outputs	Function
$\overline{OE}_1$	$\overline{OE}_2$	D_1	Y_1	
L	L	L	H	Transparent
L	L	H	L	
H	X	X	Z	Three-State
X	H	X	Z	

Note:

H = High, L = Low, X = Don't Care, Z = High Impedance

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AC CHARACTERISTICS

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Symbol	Parameter	Test Conditions	P54/74PCT827A/828A				P547PCT827B/828B				Units	Fig. No.
			MIL		COM'L		MIL		COM'L			
			Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.	Min. ¹	Max.		
t_{PLH} t_{PHL}	Propagation Delay from D_1 to Y_1 'PCT827A/B	$C_L = 50pF$ $R_L = 500\Omega$	—	10.0	—	8.0	—	6.5	—	5.0	ns	1
			—	10.0	—	8.0	—	6.5	—	5.0	ns	3
t_{PLH} t_{PHL}	Propagation Delay from D_1 to Y_1 'PCT827A/B	$C_L = 300pF^2$ $R_L = 500\Omega$	—	17.0	—	15.0	—	14.0	—	13.0	ns	1
			—	17.0	—	15.0	—	14.0	—	13.0	ns	3
t_{PLH} t_{PHL}	Propagation Delay from D_1 to Y_1 'PCT828A/B	$C_L = 50pF$ $R_L = 500\Omega$	—	9.5	—	7.5	—	6.5	—	5.5	ns	1
			—	9.5	—	7.5	—	6.5	—	5.5	ns	2
t_{PLH} t_{PHL}	Propagation Delay from D_1 to Y_1 'PCT828A/B	$C_L = 300pF^2$ $R_L = 500\Omega$	—	16.0	—	14.0	—	14.0	—	13.0	ns	1
			—	16.0	—	14.0	—	14.0	—	13.0	ns	2
t_{PZH} t_{PZL}	Output Enable Time OE to Y_1	$C_L = 50pF$ $R_L = 500\Omega$	—	17.0	—	15.0	—	9.0	—	8.0	ns	1, 7, 8
			—	17.0	—	15.0	—	9.0	—	8.0	ns	
t_{PZH} t_{PZL}	Output Enable Time OE to Y_1	$C_L = 300pF^2$ $R_L = 500\Omega$	—	25.0	—	23.0	—	16.0	—	15.0	ns	1, 7, 8
			—	25.0	—	23.0	—	16.0	—	15.0	ns	
t_{PHZ} t_{PHL}	Output Disable Time OE to Y_1	$C_L = 5pF^2$ $R_L = 500\Omega$	—	10.0	—	9.0	—	7.0	—	6.0	ns	1, 7, 8
			—	10.0	—	9.0	—	7.0	—	6.0	ns	
t_{PHZ} t_{PHL}	Output Disable Time OE to Y_1	$C_L = 50pF$ $R_L = 500\Omega$	—	19.0	—	17.0	—	8.0	—	7.0	ns	1, 7, 8
			—	19.0	—	17.0	—	8.0	—	7.0	ns	

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Notes:

1. Minimum limits are guaranteed but not tested on Propagation Delays.
2. These parameters are guaranteed but not tested.

ORDERING INFORMATION

PxxPCT	xxxx	X	X	X	
Temp. Class	Device type	Package	Temperature	Processing	
				B	MIL-STD-883, Class B
				C	0°C to +70°C
				M	–55°C to +125°C
				P	Plastic DIP
				D	CERDIP
				S	Small Outline IC
				L	Leadless Chip Carrier
				827A	Non-Inverting 10-Bit Buffer
				828A	Inverting 10-Bit Buffer
				827B	Fast Non-Inverting 10-Bit Buffer
				828B	Fast Inverting 10-Bit Buffer
				74	Commercial
				54	Military

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TECHDOC 1566